CC1310 RF

VDDS Decoupling Capacitors

- C3: 100nF
- C4: 100nF
- C5: 100nF
- C6: 22uF
- C7: 100nF

VDDR Decoupling Capacitors

- C8: 22uF
- C9: 100nF
- C16: 100nF

Place L1 and C8 close to pin 33

To use RF test connector, remove R12 and mount 0-ohm resistor R13

C24, R12 and C23 for antenna matching

CC1310 IO block placed on page 2.

Title: LAUNCHXL-CC1310

Standard: TIDA-01547

Drawn: TER, KHT

Checked: KHT
XDS110 Debugger Interface

P10 selects the voltage source for the level shifters
When powering CC1310 from the XDS supply, connect jumper between pins 1 and 2.
When powering CC1310 from the external supply, connect jumper between pins 2 and 3

M12 jumper to be mounted between pin 1 and 2 on header P10

M1-M11 jumpers to be mounted on header P4

Use P5 for debugging CC1310 with an external debugger (requires that all jumpers on P4 be removed)

Use P7 for debugging external targets (requires that all jumpers on P4 be removed)

Use P7 for debugging external targets (requires that all jumpers on P4 be removed)

XDS-RST = 0 -> output = 0
XDS-RST = 1 -> output = Hi-Z
TMS signal is bidirectional. TMS_DIR used to control direction of level shifter

DIR = H: A -> B
DIR = L: B -> A
OE = H: output = Hi-Z

TIDA-01547

Texas Instruments

Title: LAUNCHXL-CC1310

Drawn: TER

Checked: KHT

Size: A3  Rev: 1.3.0  Sheet: 3 of 4
Buttons and LEDs

User LEDs

User Buttons

BU Header

RESET

3V3 Header

Mounting Holes: 125 mil for 4-40/H2.5/H3 screws

Silkscreen

COMPANY: Texas Instruments

TITLE: MSP-EXP432P401R

DRAWN: Hito Shin

CHECKED: 

APPROVED:

3/7/2016 12:35 PM Rev: 2.0 Sheet: 2/6
EnergyTrace Software-controlled DCDC converter

Energy measurement method protected under
U.S. Patent Application 13/325,873
and subsequent patent applications
USB interface and power supply
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